

# EICROC « France » Meeting

18/09/2025



- Welcome to our colleagues from LPC Clermont Auvergne [indico...]
- Update on test bench development @ IJCLab: Firmware, setting, ...
- Status on measurements with  $^{90}\text{Sr}$   $\beta$  source (Arzoo, EuNPC2025)
- Update on infrared laser test bench at IJCLab
- Current issues: ADC pedestal, subtraction
- Update on EICROC0 testing at OMEGA and current developments
- On-going developments at LPC Clermont & CEA/Irfu/DEDIP
- Summary of EICROC0 testing meeting with BNL (08/09/25)
- General information - Discussion

### ❖ For measurements with the Beta source and the infrared laser

- Acquisition of digital data (ADC, TDC) when at least 1 channel (among the 16) sees a signal with an amplitude passing the discriminator threshold [1 Hit Bit], before Summer 2025
- To take long Beta source run [ ~10 hours to largely increase the statistics]: « Time duration » and « multiple files setting a maximum event number for each file to ease the analysis [End of July 2025]

### ❖ For measurements with the infrared laser

- Acquisition driven by the laser TrigOut signal [TTL 2V5]: requires to weld a cable on the PCB [Spare 1 & grounded], mid-August 2025 – *ceic\_en\_in\_exttrig(1)*
- « Resetb » before each event: Beginning of Sept. 2025 – *ceic\_resetb\_before\_acq(1)*
- Synchronization between the laser TrigOut signal and the 40 MHz clock? To be discussed

Caveat: with firmware/software update, we cannot use anymore Adrien's code to align the S-Curves – need previous versions

# Update on firmware development concerning updated FPGA board

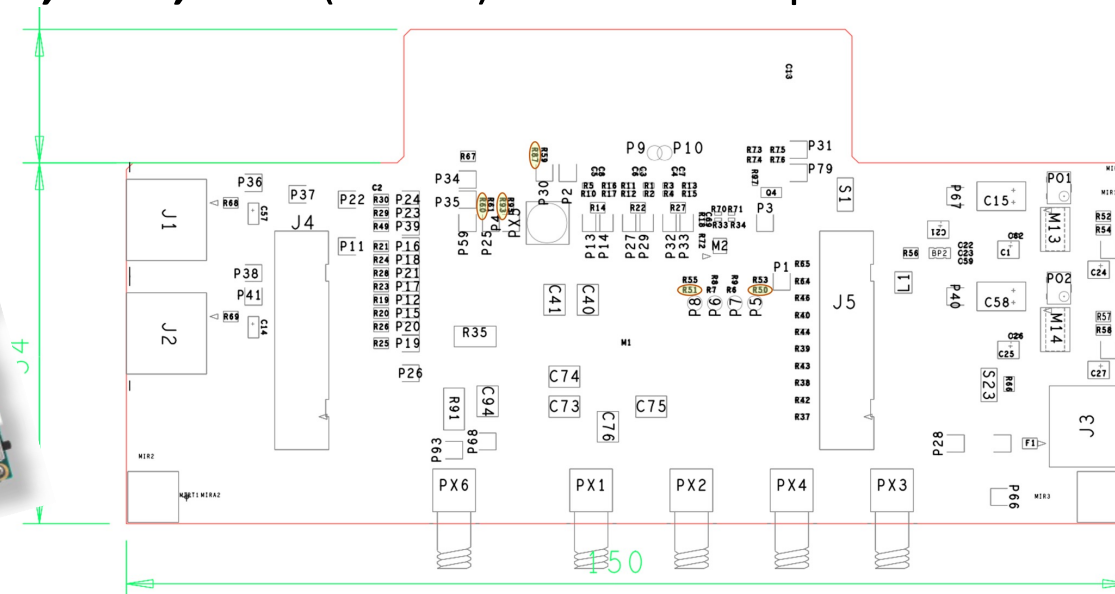
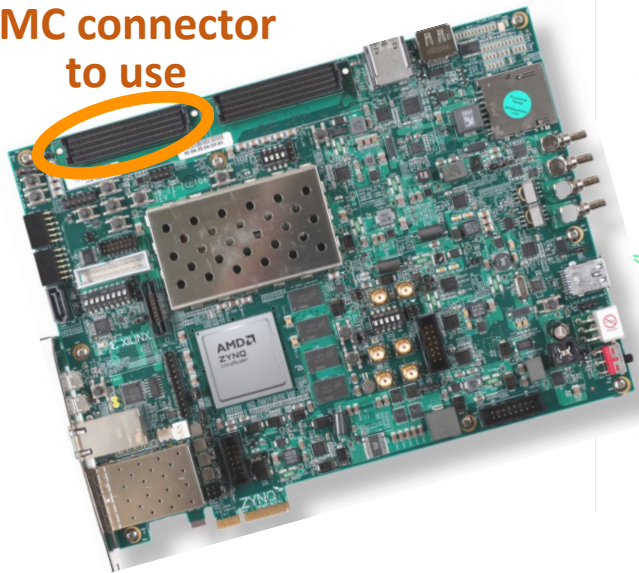
## AMD Zynq™ UltraScale+™ MPSoC ZCU106

### ➤ Firmware porting **DONE**

- For **I2C full ios compatibility** reasons (**ZCU106: 1.8V** // ZC706: 2.5V):  
physical replacement of some « pull-up » resistor values on the PCB is mandatory

➔ **R50, R51, R60, R87, R93** (2.8 k $\Omega$ ) each to be replaced with **6.04 k $\Omega$**  (size 603)

FMC connector  
to use



## ❖ With an AC-LGAD sensor:

- 1 Flip Chip: provided by BNL
- 1 HPK wire-bonded by Koji Nakamura @ KEK
- 1 BNL sensor wire-bonded by Koji Nakamura @ KEK
- 1 BNL sensor wire-bonded @ BNL: no more functional...

**Concern: Wire-Bonding as we do have EICROC0 ASIC & BNL sensors**

## ❖ Bare PCBs partially cabled: without an EICROC0 ASIC nor an AC-LGAD sensor

- 2
- 2 modified to run with ZCU106 FPGA board
- 3 shipped to BNL [June 2025] for their needs
- 2 shipped to BN [June 2025] to be shipped back to IJCLab with:
  - 1) Flip Chip (HPK etched)
  - 2) 1 HPK OR 1 BNL wire-bonded (? To be decided among us)

❖ Status of next PCB iteration with design optimized to IR laser testbench + translator for IO's compatibility with ZC706 & ZCU106, number of outputs to be increased – To be designed in close collaboration with Beng-Yun Ky

## Slow parameter settings: Bias\_PA

- ❖ Investigating issues, discovered that « tuning » Bias\_PA allowed us to see 4 probe PA simultaneously on scope with 160 MHz clock ON, whatever sensor configuration we have
  - Set the 7 bits to 45 (overall) checking that  $600 < K\_analog\_probe [mV] < 750$  [610]  
Didn't know at that time that  $Bias\_PA <6:0> = vbc\_PA <6:2> \llcorner + \llcorner vbi\_PA \llcorner <1:0> \dots$   
Need to further investigate

## Slow parameter settings: Bias\_PA

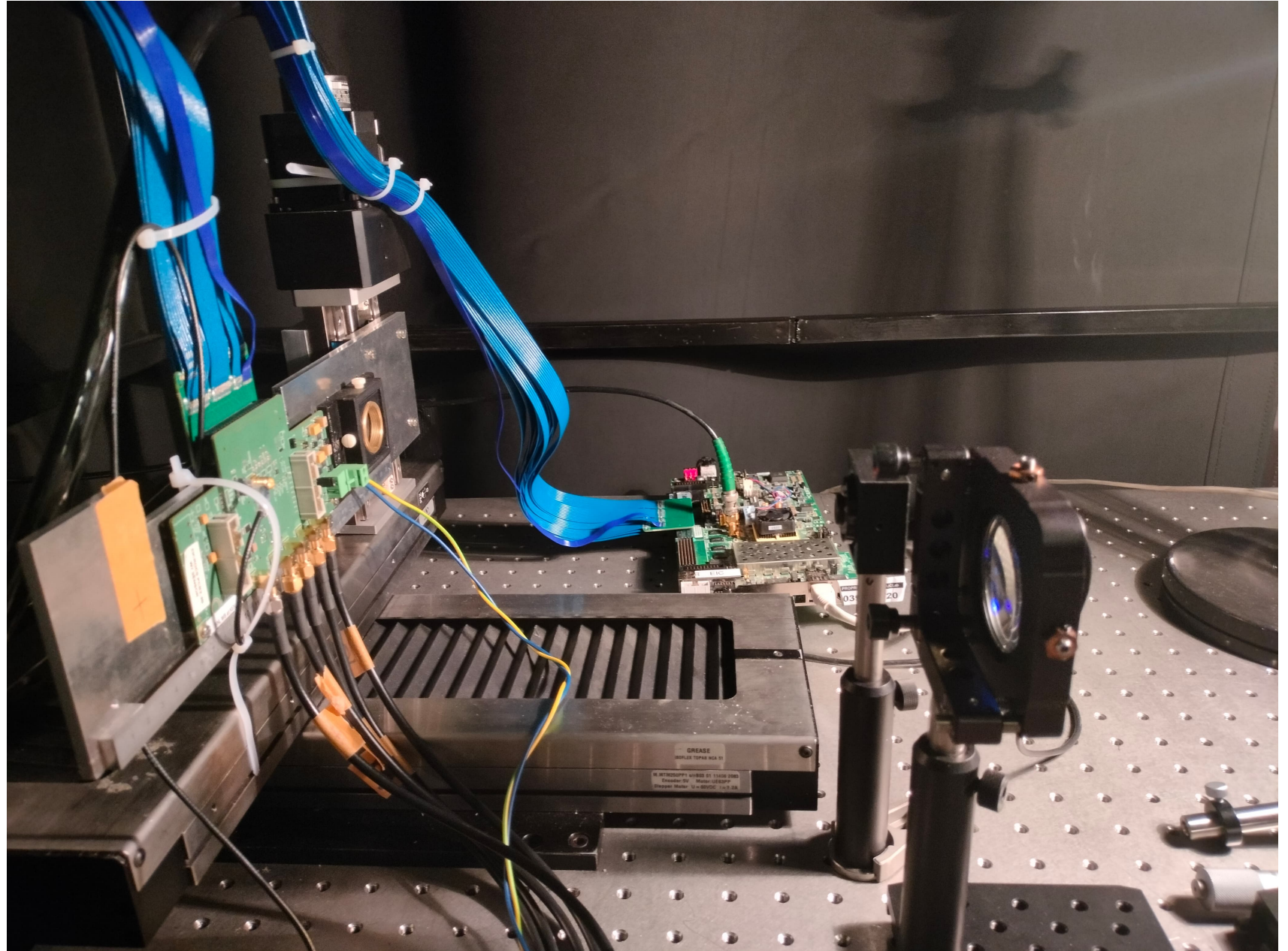
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Need to further investigate



# EICROC0 IR Laser Testbench @ IJCLab

## Team: IJClab:

- ❖ A.-S. Torrento (coordinator)
- ❖ O. Brand-Foissac
- ❖ V. Chaumat
- ❖ T. Cornet





# AC-LGAD and ASIC images with microscope

BNL WB sensor WB @ KEK

X = 11.99, Y  
= 0.98,  
Z = 241  
mm)

Sensor Edges

Sensor Center

ASIC

BNL sensor  
wire-bonded @ KEK

BNL damaged sensor

ASIC

Terminology used:

→ Aluminium Patch

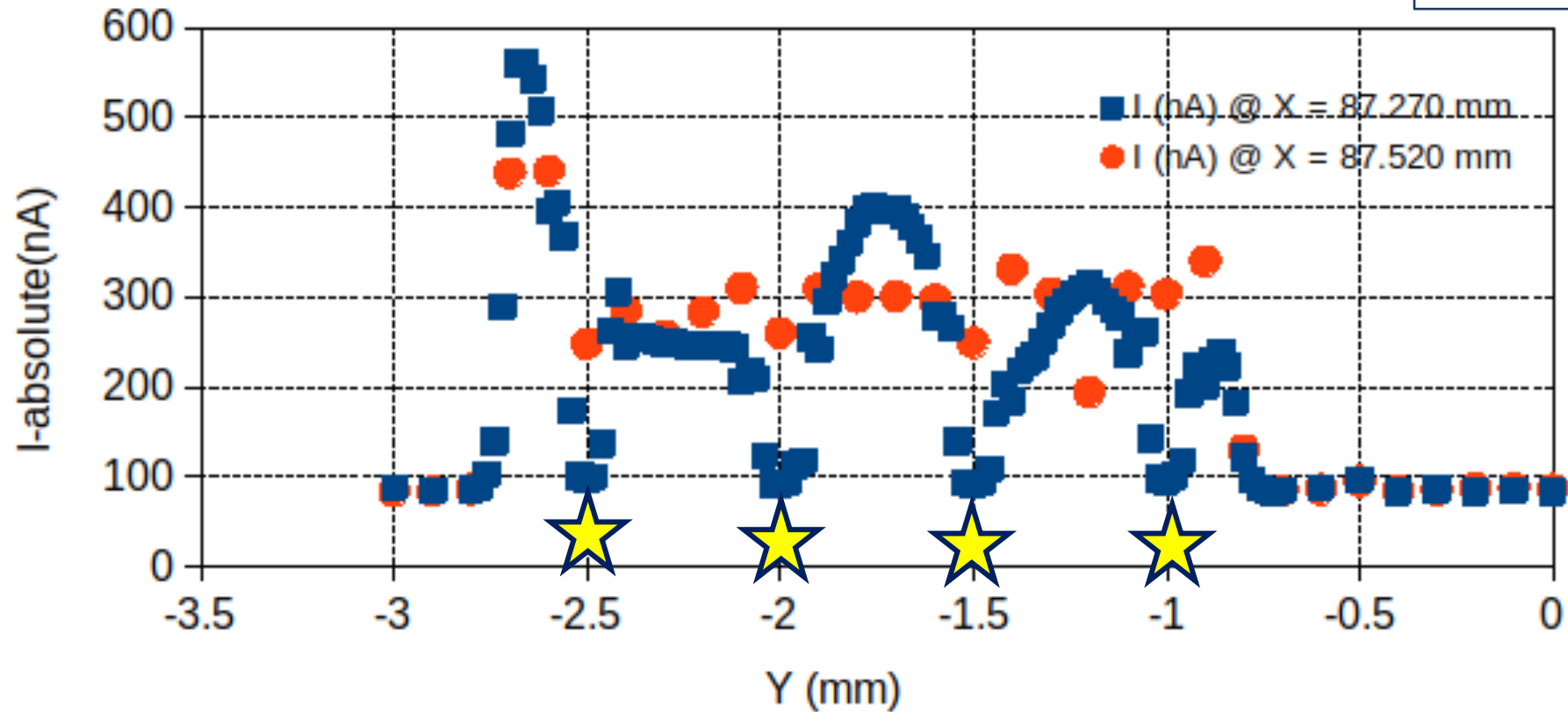
→ Pickup Electrode



# Y scan with LASER

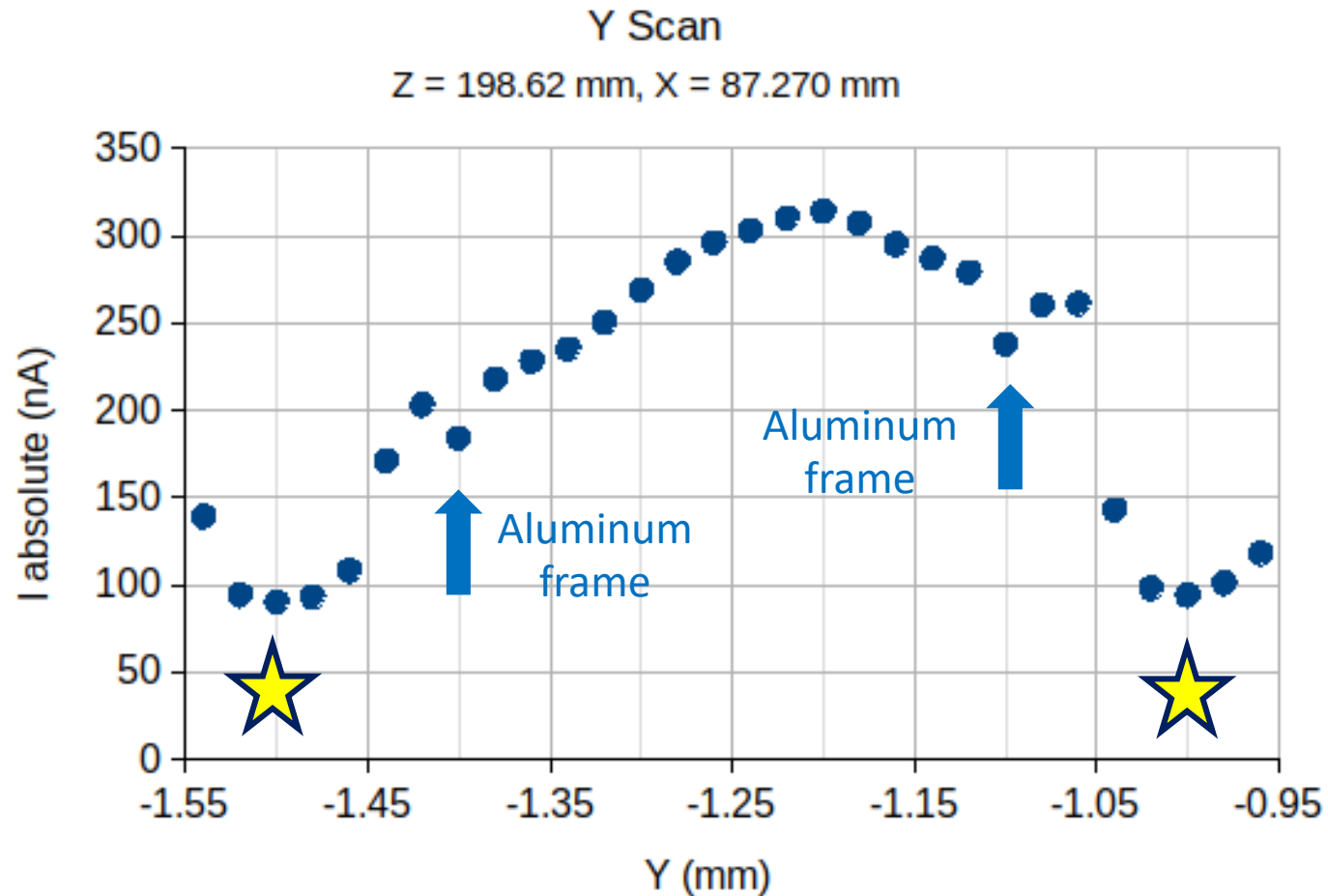
Z = 198.62 mm and different X

Laser Settings:  
1MHz, 78.50 (attenuation)



- The aim was to observe the difference between the current, once when we are scanning the column with electrodes (X = 87.270 mm / blue data range) and moving it by 250  $\mu\text{m}$  to be between the two columns and/or inter-pixel (X = 87.520 mm / orange data range).
- Full analysis will be performed with digital data -> Next Steps.

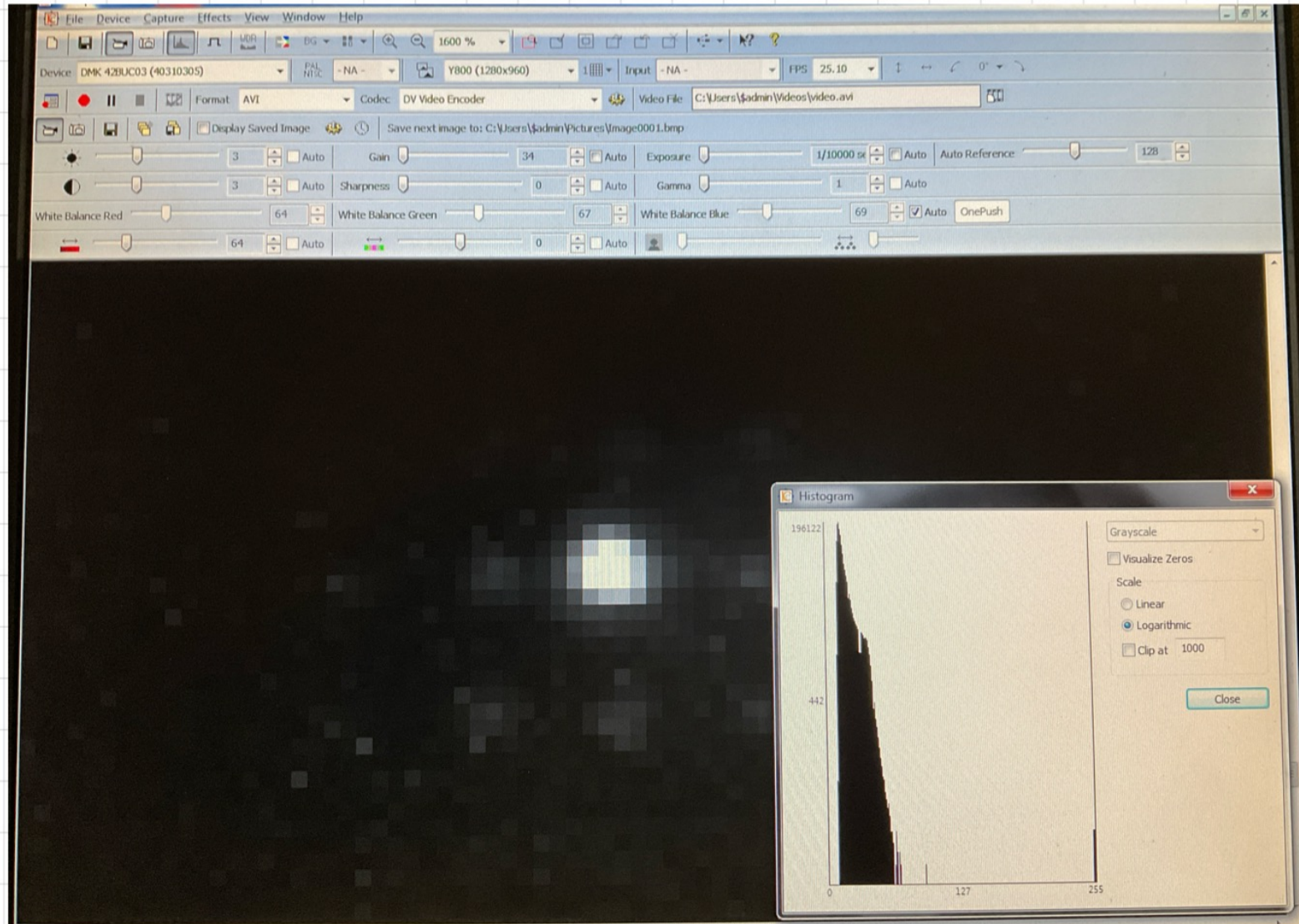
# Image Zoomed: Effect of Al patch (outside the pickup electrode) on current



- The distance between the 2 electrodes is observed  $\sim 500$   $\mu\text{m}$ .
- The current reduces while passing through Aluminum frame because of reflections.
- As, we can clearly observe the effect of Al frame (10  $\mu\text{m}$  thick) on the current, implies laser spot in Y is less than **10  $\mu\text{m}$  width**.

✓ Ready to acquire data with oscilloscope

# CMOS images with LASER centered



Laser Settings:

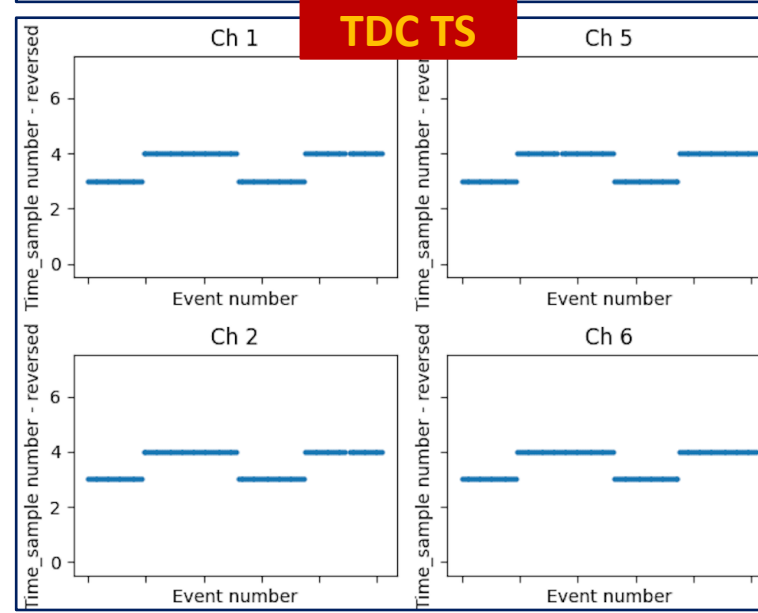
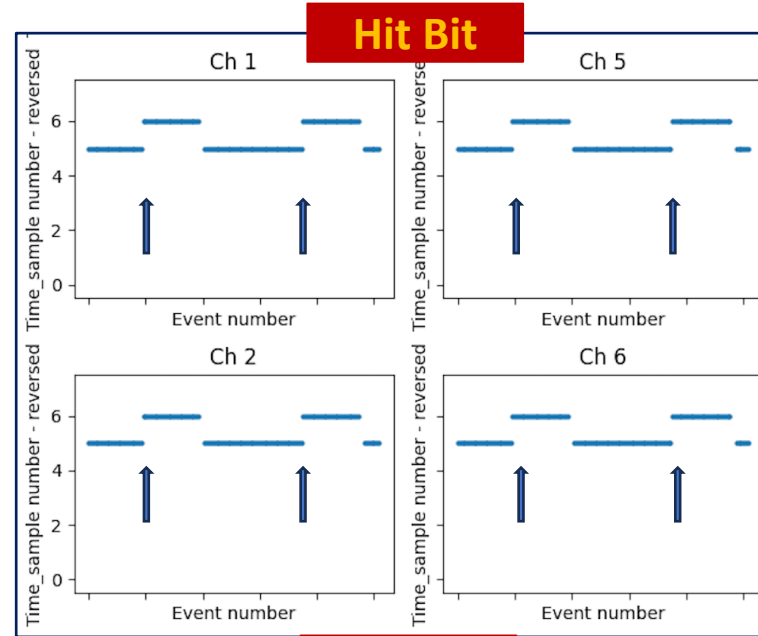
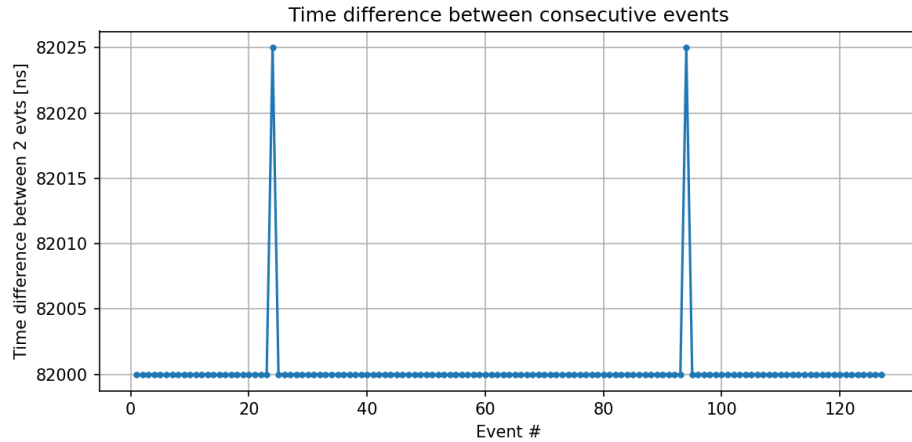
1MHz, 86 % (attenuation)

✓ Diffraction effect now removed



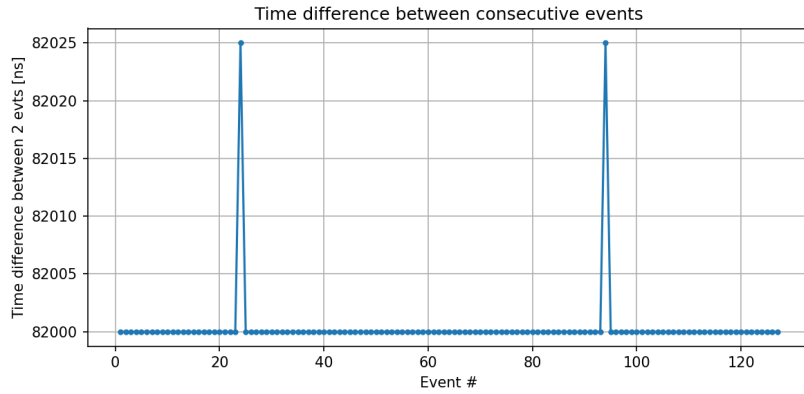
# ADC pedestal subtraction

❖ Observation of shifts of Time Sample for TDC data & Hit Bit which coincide with Time Stamp shift

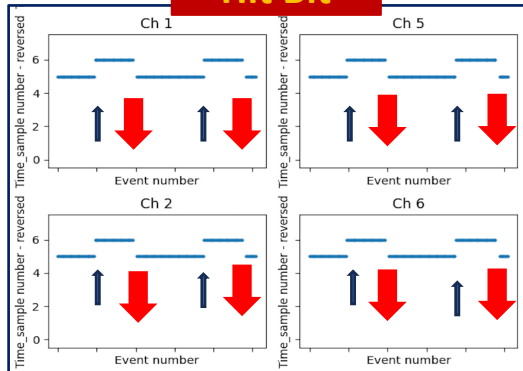


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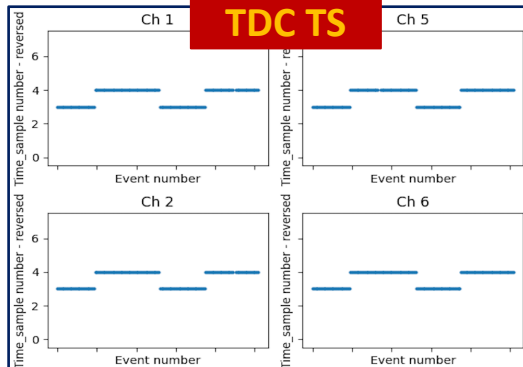
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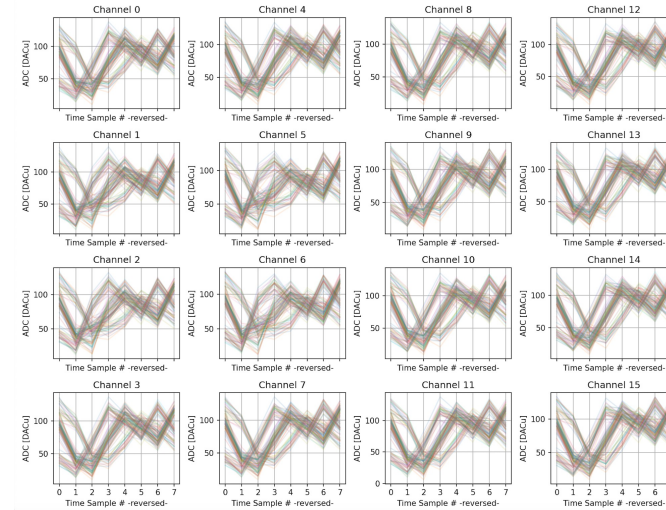
**Hit Bit**



**TDC TS**

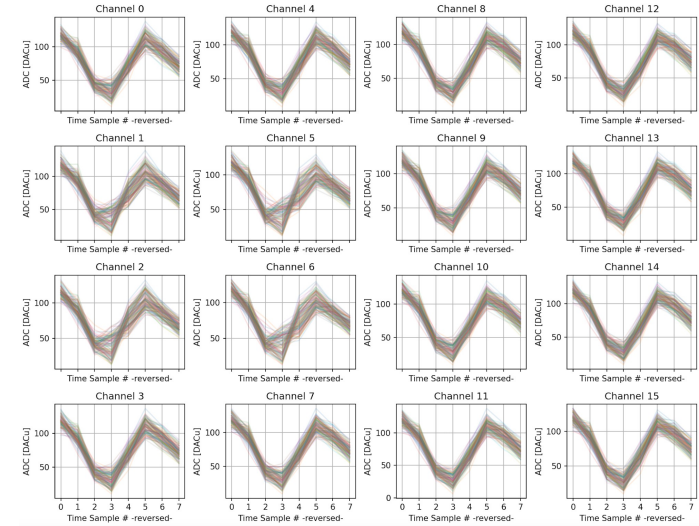


Amplitude waveforms (ADC) for ADC pedestal evaluation

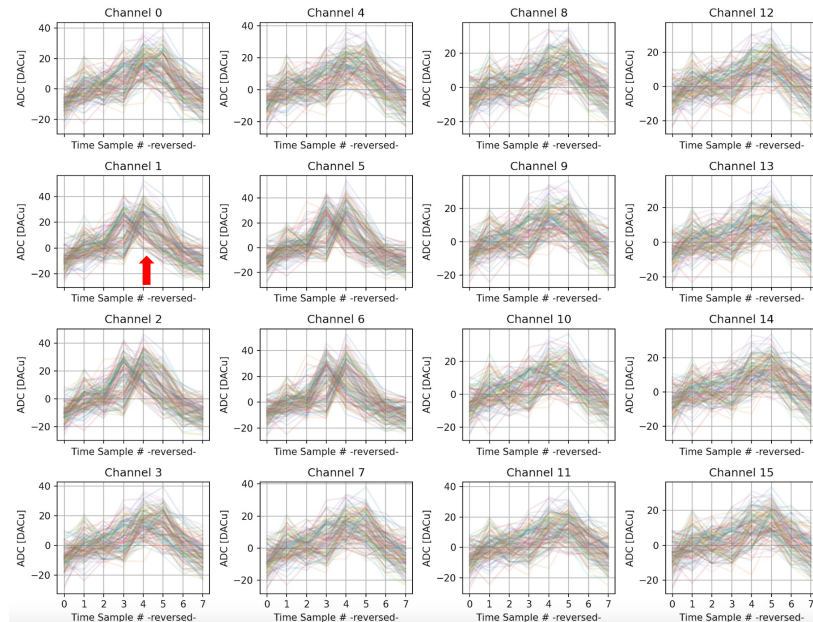


**Raw**

Amplitude waveforms (ADC) for ADC pedestal evaluation - corrected for Time Stamp difference



**Shifted**



**« Pedestal »  
subtracted**

# TDC jitter from Beta source & preliminary laser measurements



# AGENDA

- **EuNPC2025:** Sept. 21-26, 2025, Caen – Arzoo's talk (20')
- **EAP EIC (Marcella Grasso)**: Sept. 26th, 2025, IJCLab – 9:30 am  
IJCLab, LLR, LPC Clermont, OMEGA are concerned – **EICROC contribution to the next engineering run**
- **Mathieu Benoît's visit at OMEGA & IJCLab:** Sept. 29-30, 2025 => To be organized among us
- **CPAD2025:** Oct. 06-10, 2025, Philadelphia – Dominique's talk (20') [abstract accepted late August]
- **Dominique at BNL:** Oct. 11-17, 2025 – Registration being processed
- **Bi-National INFN-IN2P3 workshop:** November 21-25, LPNHE, Paris Arzoo submitted an abstract
- **« New » EIC « France » meeting:** December 01-03, 2025, IJLab (organized by GDR QCD)
- **ePIC Collaboration meeting:** mid-January, 2026, Triumph, Vancouver [To be announce]
- **TIPP2026:** Feb. 02-06, 2026, Mumbai – abstract submitted late August, no update yet

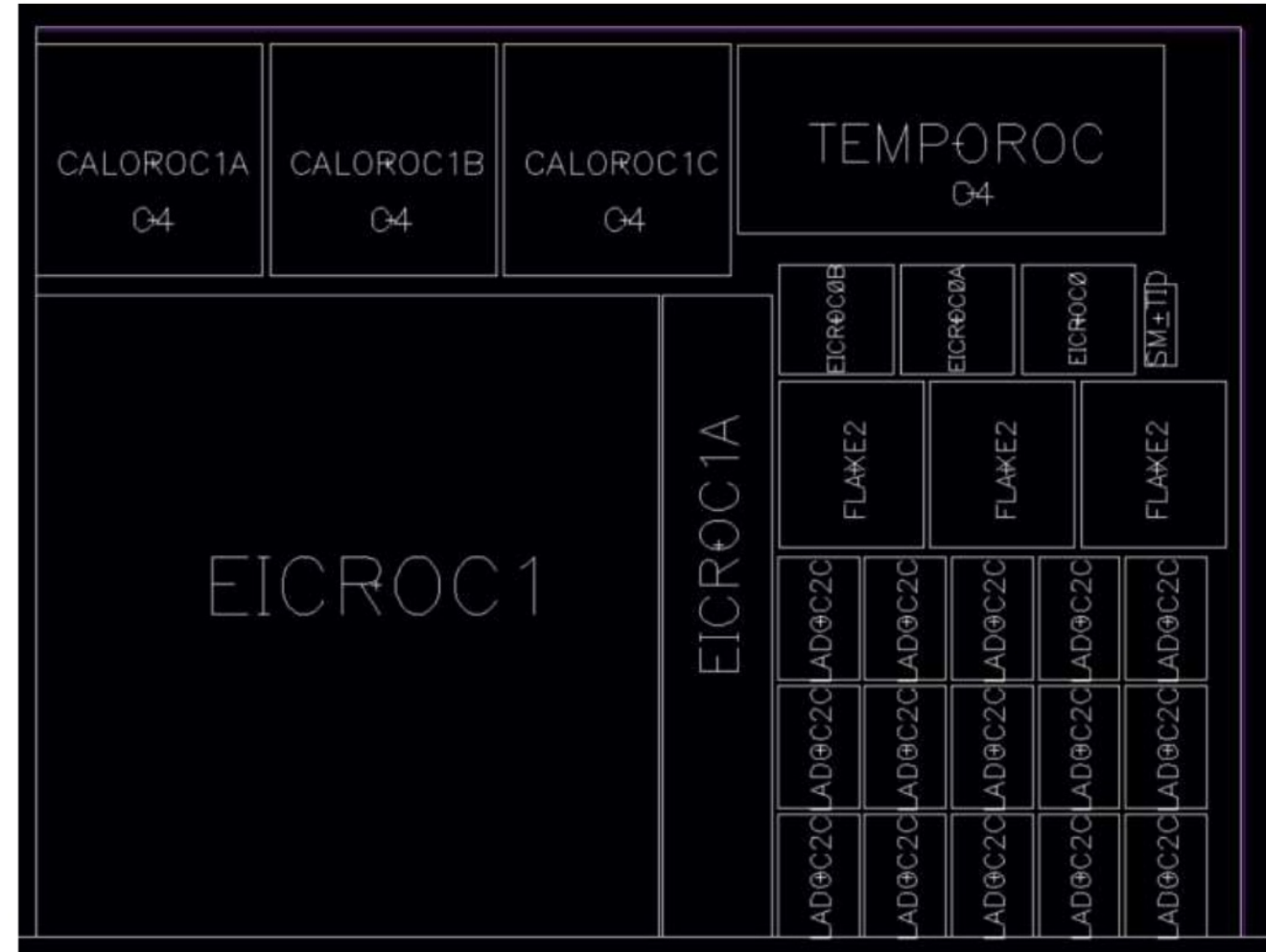
## Information - Discussion

- Currently, main concern/effort: ADC pedestal subtraction
- Need closer collaboration OMEGA – IJCLab – CEA/Irfu/DEDIP to foster EICROC0 testing & to drive next EICROC iterations including LPC Clermont team
- Seeking for a postdoctoral researcher working at IJCLab: characterization of pixelated AC-LGAD with EICROC & simulation activities (i.e. exclusive process including far-forward detectors)  
(2,5 years, starting Feb. 2026)  
*Arzoo's contract is extended until January 9th, 2026.*

Back-up



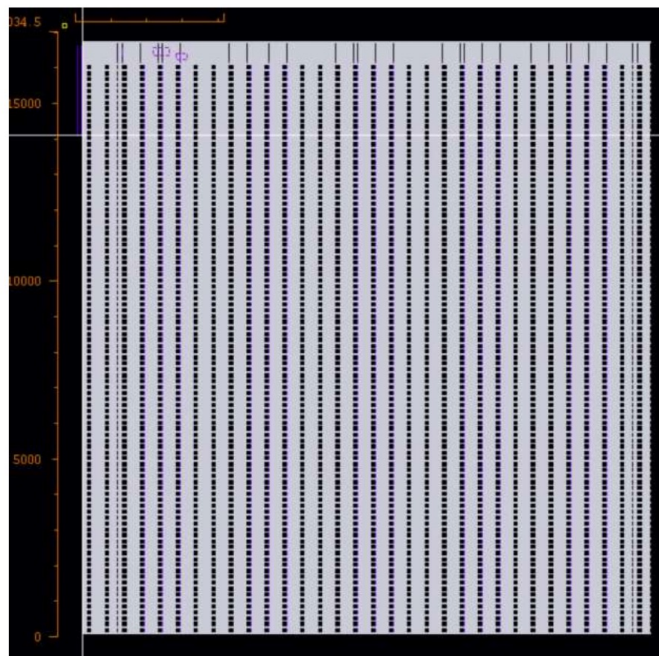
- TSMC now requires to fully populate the reticle
  - Cost ~300 k€
- For EIC we have
  - 1 EICROC1 32x32
  - 1 EICROC1A 4x32
  - 3 EICROC0/A/B 4x4
  - 3 CALOROC1A/B/C
  - ~70% of reticle area
  - EICROC1 is 40% of reticle area
  - gds files loaded end of may
- Still administrative issues delaying the start of fabrication



- **EICROC0A** same as EICROC0 with more testability
  - Each pixel can be by-passed by SC (clock is then turned off)
  - Buffers in SC to allow extension to 4x32
  - Larger dynamic range in pulse injection
- **EICROC0B**
  - Same preamp/discriminator/TDC/integrator
  - ADC and driver replaced by peak sensing and Wilkinson ADC
  - Currently ADC path  $\sim 1$  mW/ch becomes 200  $\mu$ W/ch
- Will be fabricated with EICROC1 below

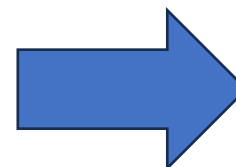
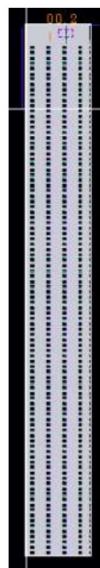


- 32x32 chip : final dimensions
- Goal :
  - test full-scale chip analog performance (IR drops)
  - Allow final sensor characterization
  - Test interface with DAQ : fast commands and 320 Mb/s data output
  - Progress on module/front-end boards
- Caveats ;
  - Not (yet) zero-suppressed data
  - Still 2mW/ch
  - Still analog-on-top



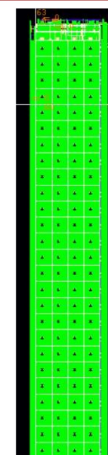
- Designed as 8 blocks of 4x32
  - Read out sequentially, like EICROC0
  - Pixel similar to EICROC0A
  - 8 CLPS outputs at 40 MHz
  - Clock tree for isochronous calib\_pulse distribution

- Common balcony (End of column)
  - Biases and slow control
  - New : fast command decoder (clock, calib\_pulse, enable\_acquisition, start\_readout)
  - Backup clock and cmd\_pulse inputs available
  - New : 320 MHz serializer for 1 CLPS output



### EICROC1A variant

- Full block of 4x32 of EICROC1 with old EICROC0 pinout
  - Same balcony as EICROC0A (same slow control parameters)
  - Same testboard and DAQ as EICROC0
  - Allows to test columns specific effects (IR drops)







# Pixelated AC-LGAD Read Out with EICROC0: on-going characterization activities

at IJCLab

## ❖ Infrared laser test bench development:

- Olivier Brand-Foissac
- Vincent Chaumat
- Thomas Cornet
- D. M.
- Arzoo Sharma
- Ana-Sofia Torrento

## ❖ Beta source ( $^{90}\text{Sr}$ ) test bench:

- D. M.
- Laurent Serin
- Arzoo Sharma
- Beng-Yun Ky

## Other ePIC Roman Pots activities at IJCLab: cooling studies & associated mechanics

- Raphaël Dupré
- Christine Le Galliard